

PATENT

Docket No.: M4065.0127/P127-A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Kie Ahn et al.

Serial No.: Not Yet Assigned

Group Art Unit: 2815

Filed: September 12, 2000

Examiner: Not Yet Assigned



For: SILICON MULTI-CHIP
MODULE PACKAGING WITH
INTEGRATED PASSIVE
COMPONENTS AND METHOD
OF MAKING

Assistant Commissioner for Patents
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT (IDS)

Dear Sir:

Pursuant to 37 C.F.R. 1.56, the attention of the Patent and Trademark Office is hereby directed to the references listed on the attached PTO-1449. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the references be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

- x 1. This Information Disclosure Statement is being filed within three months of the U.S. filing date OR within three months of the date of entry of the national stage as set forth in 37 C.F.R. 1.491, OR before the mailing date of a first Office Action on the merits, whichever event occurs last. No certification or fee is required. 37 C.F.R. 1.97(b).
2. This Information Disclosure Statement is being filed more than three months after the U.S. filing date, OR more than three months after the date of entry of the national stage, AND after the mailing date of the first Office Action on the merits, whichever occurs first, but before the mailing date of a Final Rejection or Notice of Allowance. 37 C.F.R. 1.97(c).

- _____ a. I hereby certify that each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement. 37 C.F.R. 1.97(e)(1).
- _____ b. I hereby certify that no item of information in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to my knowledge after making reasonable inquiry, was known to any individual designated in 37 C.F.R. 1.56(c) more than three months prior to the filing of this Information Disclosure Statement. 37 C.F.R. 1.97(e)(2).
- _____ c. Attached is our check in the amount of _____ in payment of the fee under 37 C.F.R. 1.17(p). Please charge any fee deficiencies, or credit any overpayment, to Deposit Account No. 4 - 1073 as needed to ensure consideration of the Information Disclosure Statement. Two duplicate copies of this paper are attached.
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☐ 4. Translations of the non-English language references are enclosed.

☐ Full

☐ Partial

☐ Summary/abstract

☒ 5. A copy of the references can be found in U.S. Patent Application No. 09/241,061.

Dated: September 12, 2000

Respectfully submitted,

By 

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